

PRODUCT SPECIFICATION

7.0" TN TFT LCD MODULE MODEL: YDP LCD TN 12 700 R 002



< ◇ > Preliminary Specification

< ◆ > Finally Specification

CUSTOMER'S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY
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knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2021.05.06	ZJW	Initial Release	
1.1	2022.11.02	LQ	Modify IC Add Weight Add Current Consumption Add CIE Value Modify AC Characteristics Modify Outline Drawing(B)	P4 P4 P5 P6 P11 P25

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver Ics and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	7.0"	
LCD type	TN TFT	
Display Mode	Transmissive / Normally White	
Resolution	800 RGB x 480	Pixels
View Direction	12 O'CLOCK	Best Image
Gray Scale Inversion Direction	6 O'CLOCK	
Module Outline	165(H) x 104(V) x 3.5(T) (Note1)	mm
Active Area	153.84(H) x85.63(V)	mm
Pixel Size	192.3 x178.4	um
Pixel Arrangement	RGB Vertical stripe	
Polarizer Surface Treatment	Anti-glare	
Display Colors	16.7M	
Interface	24bits-RGB Interface	
Driver IC	EK79716&EK73202	
With or Without Touch Panel	Without	-
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	128	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Power supply voltage	VDD	-0.5	5.0	V
Storage temperature	T _{STG}	-30	+80	°C
Operating temperature	T _{OP}	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	VDD	3.0	3.3	3.6	V
Logic Low input voltage	V _{IL}	GND	-	0.3*VDD	V
Logic High input voltage	V _{IH}	0.7*VDD	-	VDD	V
Low level output voltage	V _{OL}	VDD-0.4	-	-	V
Hight level output voltage	V _{OH}	-	-	GND+0.4	V
Current Consumption All Black	Logic	I _{CC} + I _{IN}	65	-	mA
	Analog				

5. Backlight Characteristic

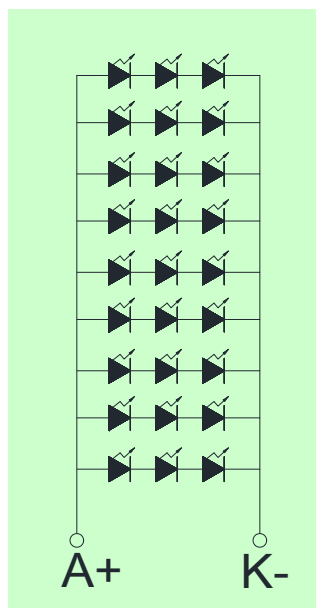
5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Backlight Voltage	V _{LED}	Ta=25 °C, I _F =20mA/ LED	8.4	9.6	10.2	V
Backlight Current	I _{LED}	Ta=25 °C, V _F =3.2V/ LED	-	180	-	mA
Power dissipation	P _D	-	-	1728	-	mW
LED Life Time(25 °C)	-	-	-	30000	-	Hr
Uniformity	Avg	-	-	80	-	%
Drive method	Constant current					
LED Configuration	27 White LEDs (3 LEDs in string and 9 groups in parallel)					

Note: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25 ± 2 °C, 60%RH ± 5%, I_F=20mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

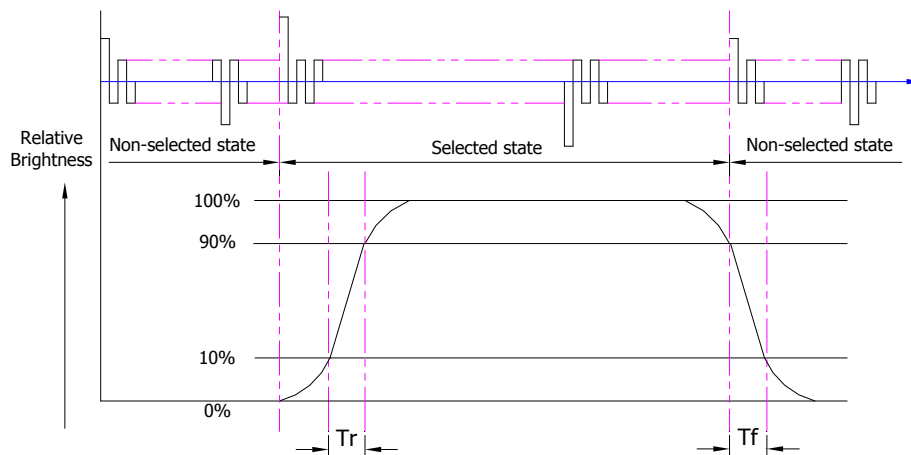
6.1. Optical Characteristics

Ta=25°C, VDD=3.3V

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle $\theta_x = \varphi_y = 0^\circ$	800	1000	-	cd/m ²
	Contrast ratio(See 7.3)		CR		-	500	-	
	Response time (See 7.2)		T _R +T _F		-	25	-	ms
	Chromaticity Transmissive (See 7.5)	Red	X _R		0.542	0.592	0.642	
			Y _R		0.277	0.327	0.377	
		Green	X _G		0.295	0.345	0.395	
			Y _G		0.562	0.612	0.662	
		Blue	X _B		0.096	0.146	0.196	
			Y _B		0.085	0.135	0.185	
		White	X _W		0.259	0.309	0.359	
			Y _W		0.318	0.368	0.418	
	Viewing Angle (See 7.4)	Horizontal	θ _{x+}	Center CR≥10	60	70	-	Deg.
			θ _{x-}		60	70	-	
		Vertical	φ _{y+}		50	60	-	
φ _{y-}			50		60	-		
NTSC				-	50	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

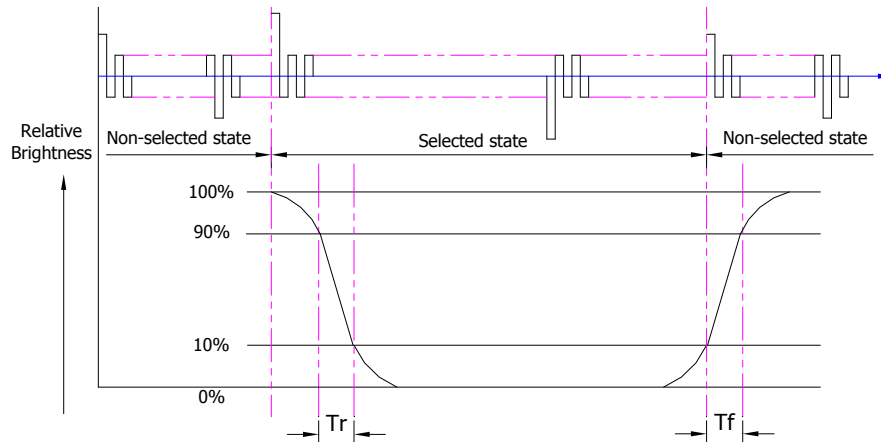


T_r is the time it takes to change from non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

T_f is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



T_r is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%;

T_f is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

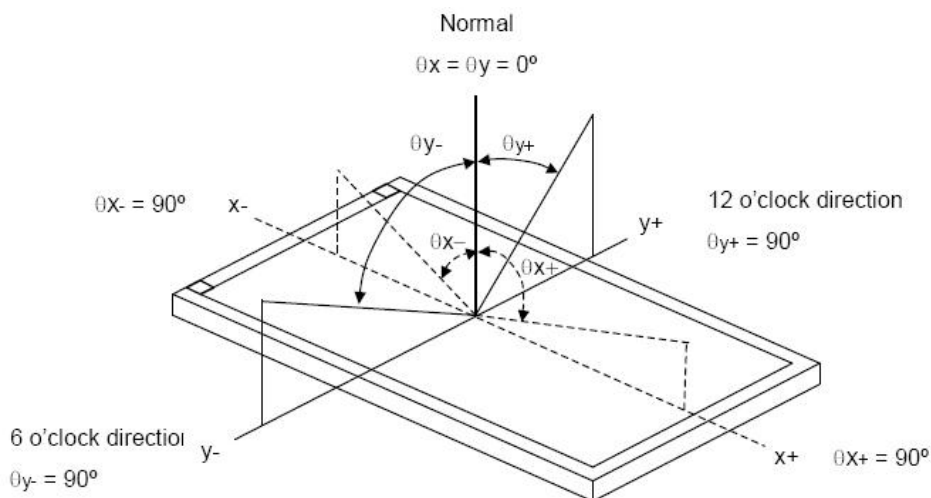
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



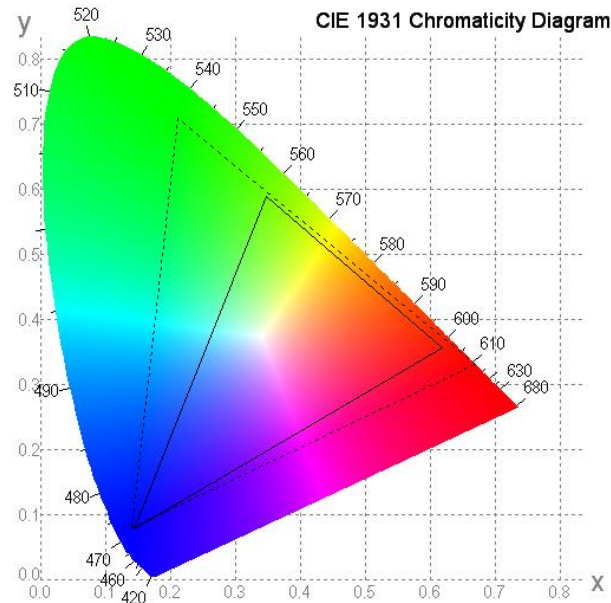
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

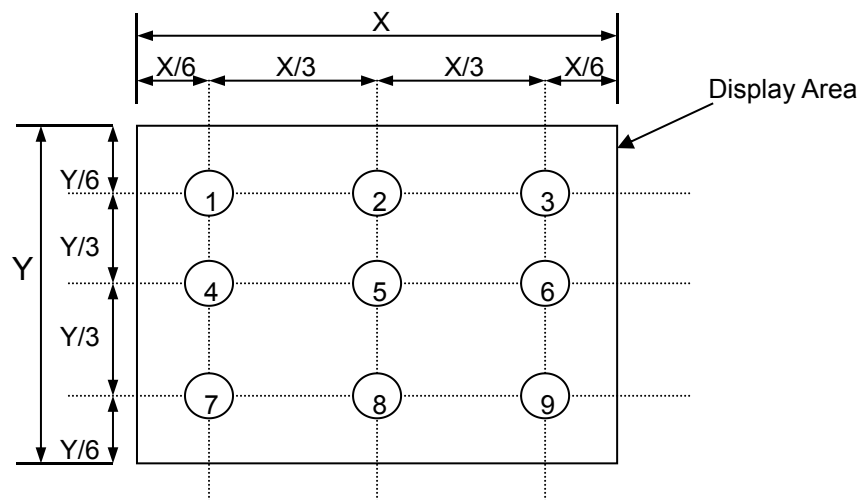
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_V = \text{average } (L_{P1}:L_{P9})$

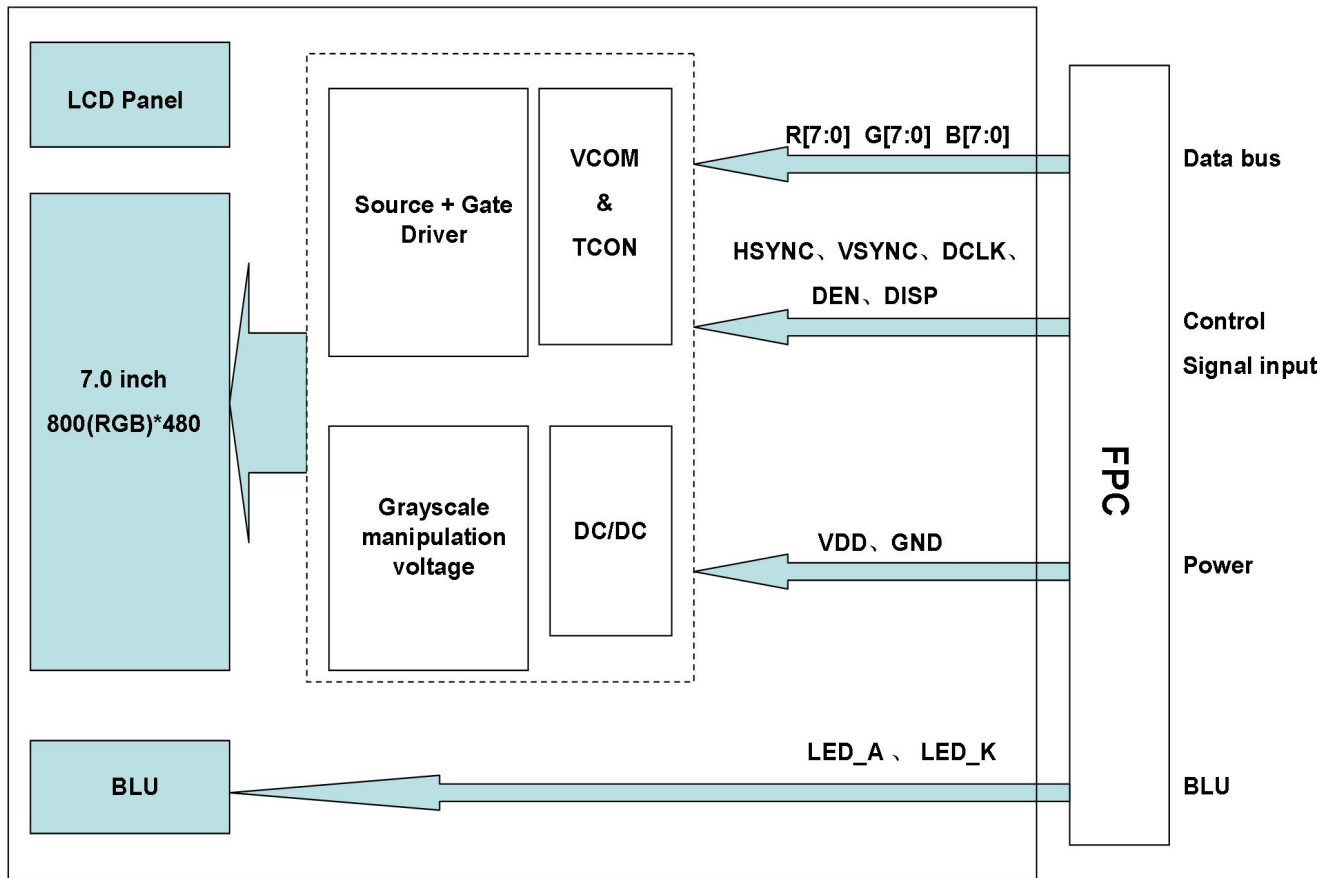
6.6.2. Uniformity = Minimal ($L_{P1}:L_{P9}$) / Maximal ($L_{P1}:L_{P9}$) * 100%

6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



8. Interface Pins Definition

No.	Symbol	Function
1	LED-K	LED backlight(Cathode)
2	LED-A	LED backlight(Anode)
3	GND	Ground
4	VDD	Power supply
5	R0	Red Data
6	R1	Red Data
7	R2	Red Data
8	R3	Red Data
9	R4	Red Data
10	R5	Red Data
11	R6	Red Data
12	R7	Red Data
13	G0	Green Data
14	G1	Green Data
15	G2	Green Data
16	G3	Green Data
17	G4	Green Data
18	G5	Green Data
19	G6	Green Data
20	G7	Green Data
21	B0	Blue Data
22	B1	Blue Data
23	B2	Blue Data
24	B3	Blue Data
25	B4	Blue Data
26	B5	Blue Data
27	B6	Blue Data
28	B7	Blue Data
29	GND	Ground
30	DCLK	Dot data clock
31	DISP	Display on/off. DISP=1:Display on.
32	HSYNC	Horizontal sync input in RGB mode(short to GND if not used)
33	VSYNC	Vertical sync input in RGB mode(short to GND if not used)
34	DEN	Data Enable. Active high to enable the data input bus.
35	NC	No connection
36	GND	Ground
37	NC(XR)	No connection
38	NC(YD)	No connection
39	NC(XL)	No connection
40	NC(YU)	No connection

9. AC Characteristics

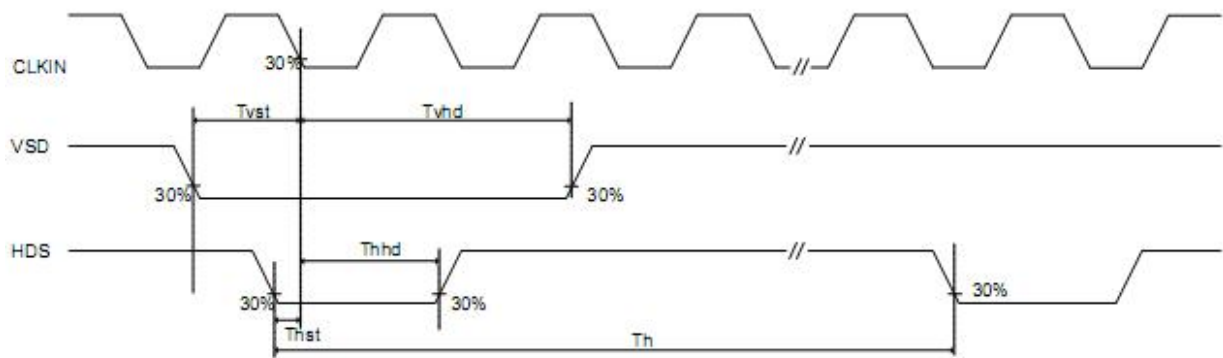
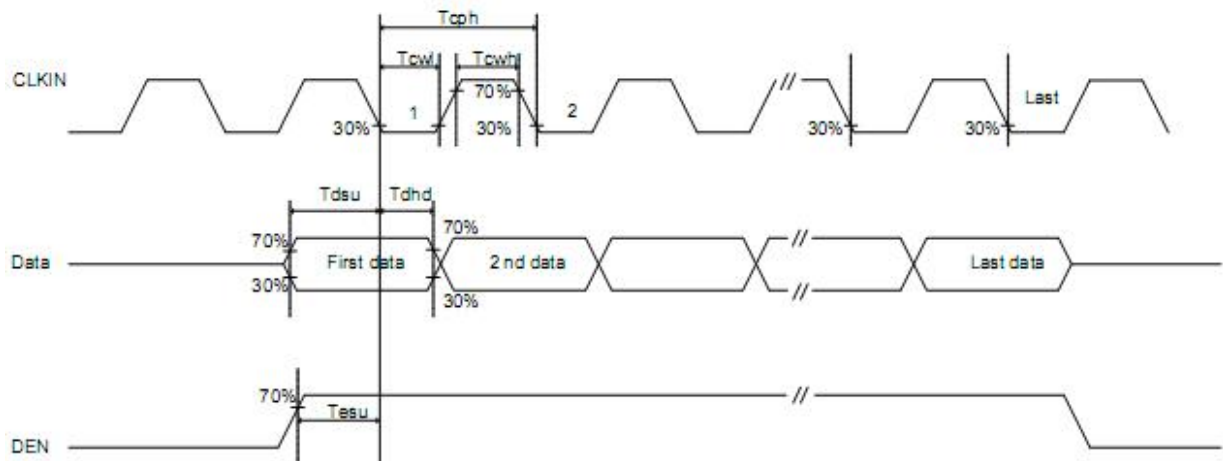
1) AC Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
VDD Power On Slew rate	T _{POR}	From 0V to 90% VDD	-	-	20	ms
RSTB pulse width	T _{RST}	CLKIN = 50MHz	50	-	-	us
CLKIN cycle time	T _{cph}	-	20	-	-	ns
CLKIN pulse duty	T _{cwh}	-	40	50	60	%
VSD setup time	T _{vst}	-	8	-	-	ns
VSD hold time	T _{vhd}	-	8	-	-	ns
HSD setup time	T _{hst}	-	8	-	-	ns
HSD hold time	T _{hhd}	-	8	-	-	ns
Data set-up time	T _{dsu}	DR[7:0], DG[7:0], DB[7:0] to CLKIN	8	-	-	ns
Data hold time	T _{dhd}	DR[7:0], DG[7:0], DB[7:0] to CLKIN	8	-	-	ns
DEN setup time	T _{esu}	-	8	-	-	ns
DEN hold time	T _{ehd}	-	8	-	-	ns
Output stable time	T _{sst}	10% to 90% target voltage. CL=120pF, R=10K ohm	-	-	6	us

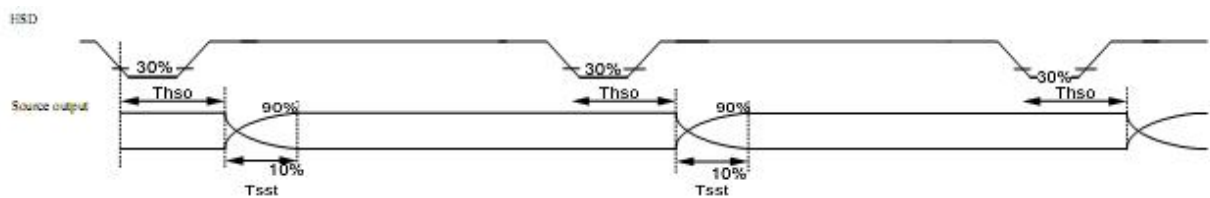
2) Timing Table

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
CLKIN Frequency(Dual gate)	F _{clk}	VDD = 3.3V	-	29.2	46.5	MHz
CLKIN Cycle Time(Dual gate)	T _{clk}	-	22	34	-	ns
CLKIN Frequency(cascade)	F _{clk}	VDD = 3.3V	-	29.2	40	MHz
CLKIN Cycle Time(cascade)	T _{clk}	-	25	34	-	ns
CLKIN Pulse Duty	T _{cwh}	T _{clk}	40	50	60	%
Time from HSD to Source Output	T _{hso}	-	-	46	-	CLKIN
Time from HSD to LD	T _{hld}	-	-	46	-	CLKIN
Time from HSD to STV	T _{hstv}	-	-	2	-	CLKIN
Time from HSD to CKV	T _{hckv}	-	-	20	-	CLKIN
Time from HSD to OEV	T _{hoev}	-	-	4	-	CLKIN
LD Pulse Width	T _{wld}	-	-	10	-	CLKIN
CKV Pulse Width	T _{wckv}	-	-	66	-	CLKIN
OEV Pulse Width	T _{woev}	-	-	74	-	CLKIN

3) Timing Waveform

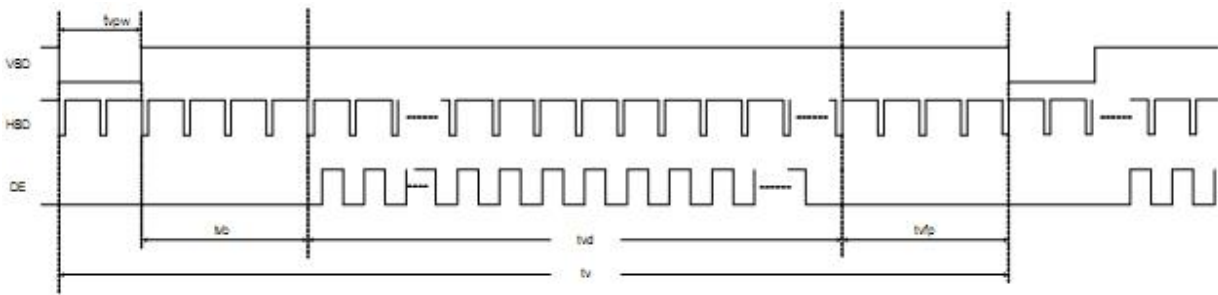


Input Clock and Data Timing Diagram

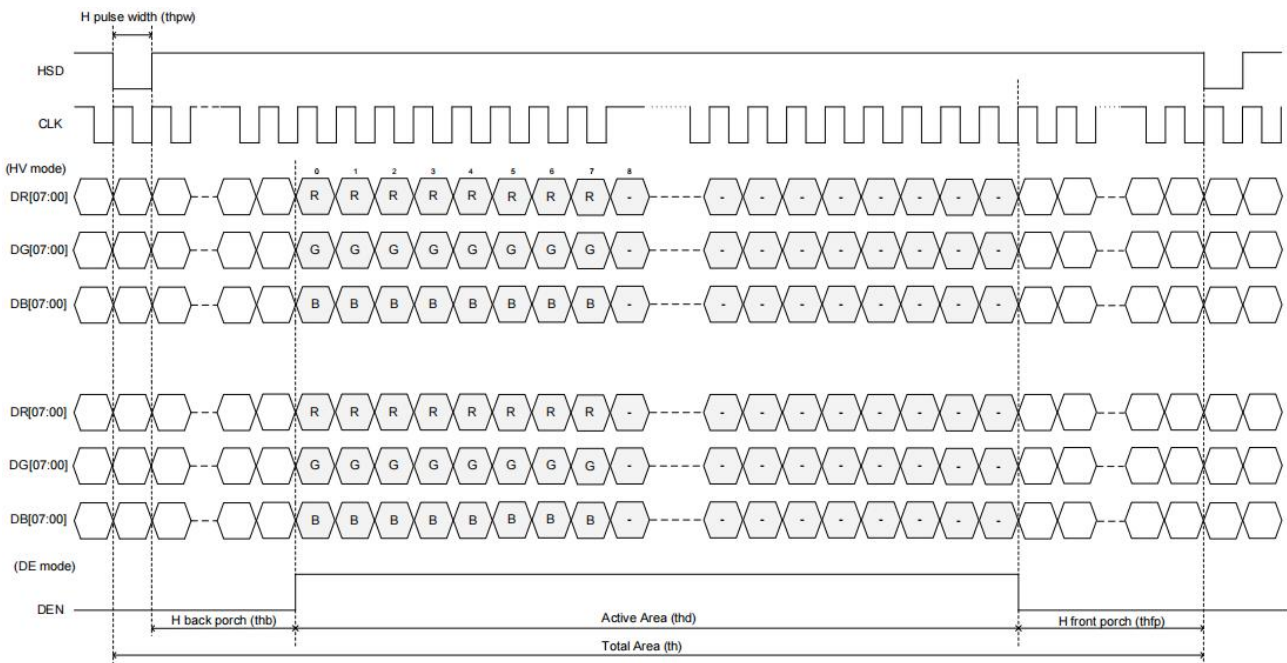


4) Data Input Format

Vertical input timing

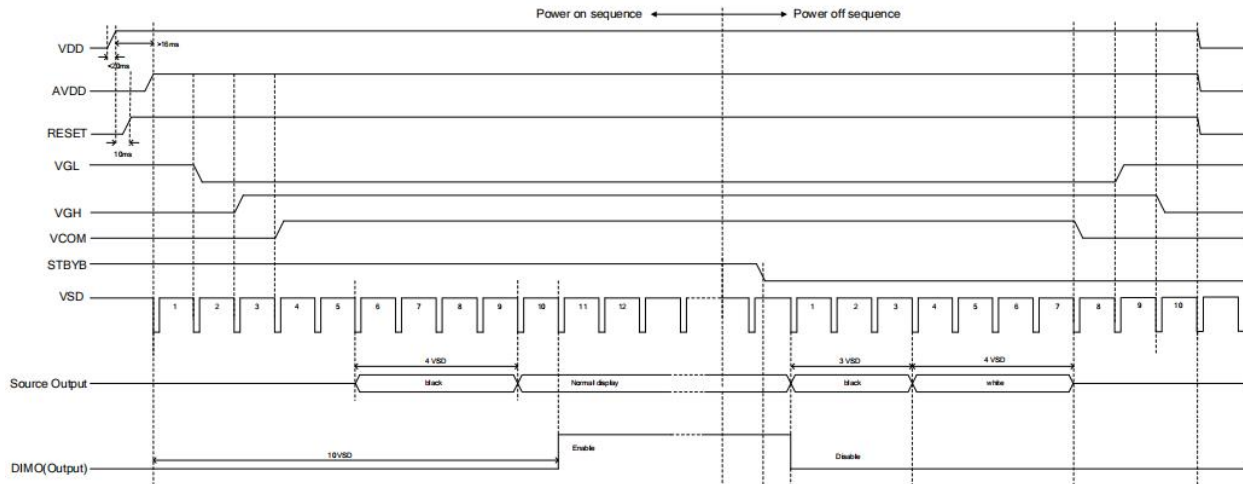


Horizontal input timing

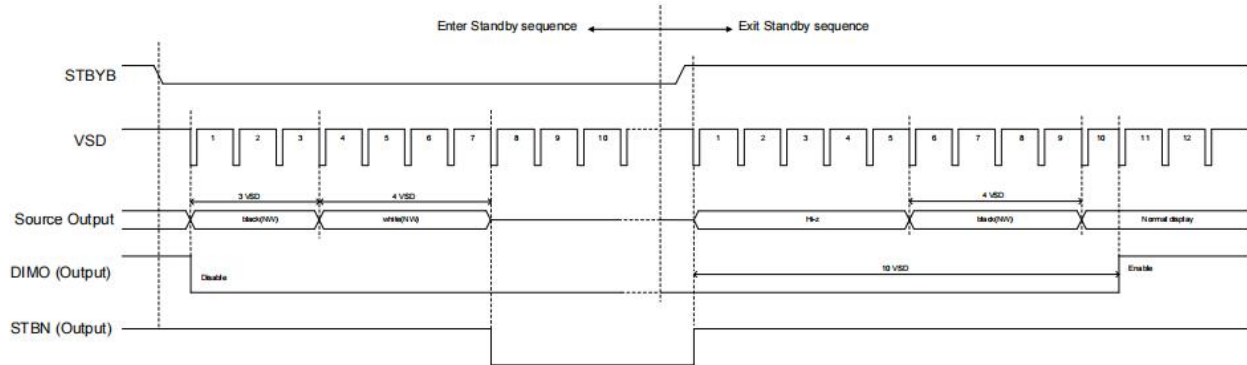


5) Power On/Off Sequence

Power-On/Off Timing Sequence



Enter and Exit Standby Mode Sequence



6) Timing Characteristic

Horizontal Timing

Parameter	Symbol	Value			Unit	Note
Horizontal display area	thd	800			DCLK	
DCLK frequency	fclk	Min.	Typ.	Max		
		28.2	29.2	46.5	MHz	
1 Horizontal Line	th	908	928	1088	DCLK	When user use SYNC mode. thb+thpw=88 DCLK is fixed.
HSD pulse width	thpw	1	48	87		
HSD Back Porch (Blanking)	thb	87	40	1		
HSD Front Porch	thfp	20	40	200		

Vertical Timing

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Vertical display area	tvd	480			H	
VSD period time	tv	517	525	712	H	When user use SYNC mode. tvpw+tvb=32H is fixed.
VSD pulse width	tvpw	1	1	3	H	
VSD Back Porch (Blanking)	tvb	31	31	29	H	
VSD Front Porch	tvfp	5	13	200	H	

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2.Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II.

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3.Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

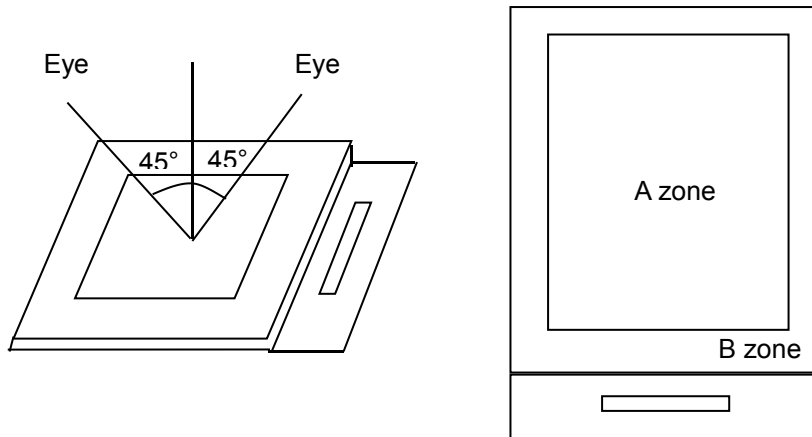
10.5. Standard of the Product Visual Inspection

10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm $\pm$ 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

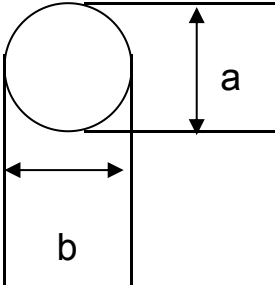


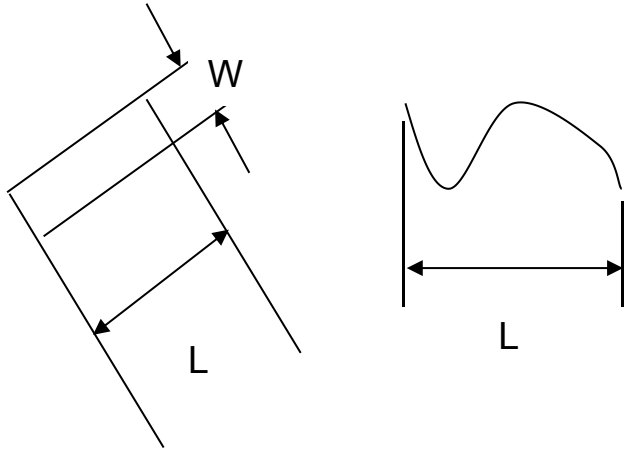
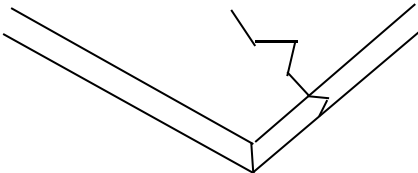
10.5.2. Basic principle:

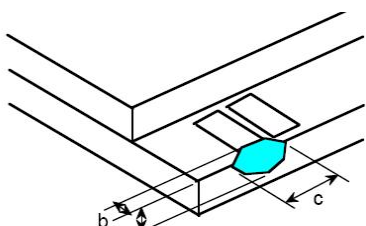
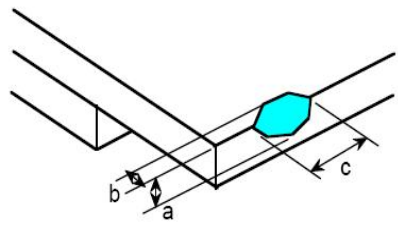
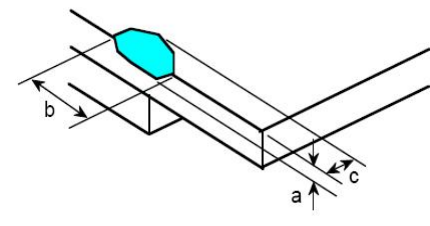
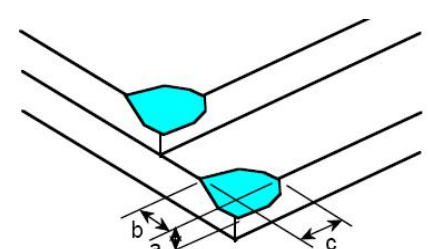
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

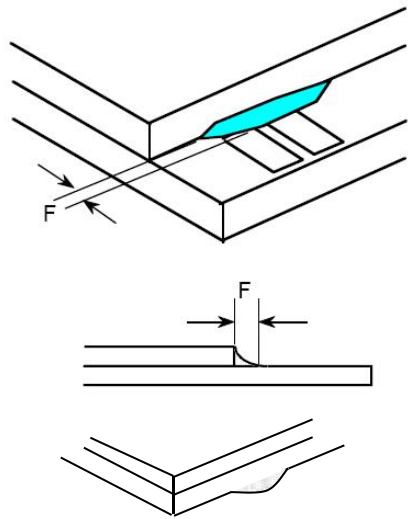
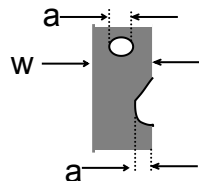
10.5.2.2. New item must be added on time when it is necessary.

10.6. Inspection Specification

No.	Item	Criteria (Unit: mm)									
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)		<table><tr><th>Size \ Area</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \varphi \leq 0.50$</td><td>N ≤ 3</td></tr><tr><td>$0.50 < \varphi$</td><td>0</td></tr></table>	Size \ Area	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.50$	N ≤ 3	$0.50 < \varphi$	0
		Size \ Area	Acc. Qty								
$\varphi \leq 0.20$	Ignore										
$0.20 < \varphi \leq 0.50$	N ≤ 3										
$0.50 < \varphi$	0										
		$\varphi = (a + b) / 2$ Distance between 2 defects should more than 5mm apart.									

02	Electrical Defect (Minor defect)	<table><tr><th rowspan="2">Bright dot</th><th>Display Area</th><th>Total</th><th rowspan="3">Note1</th></tr><tr><th>$N \leq 2$</th><th>$N \leq 2$</th></tr><tr><th>Dark dot</th><th>$N \leq 4$</th><th>$N \leq 4$</th></tr><tr><th>Total dot</th><th>$N \leq 4$</th><th>$N \leq 4$</th></tr><tr><th>Mura</th><td colspan="2">Not visible through 5% ND filters.</td><th>Note 2</th></tr></table> Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.	Bright dot	Display Area	Total	Note1	$N \leq 2$	$N \leq 2$	Dark dot	$N \leq 4$	$N \leq 4$	Total dot	$N \leq 4$	$N \leq 4$	Mura	Not visible through 5% ND filters.		Note 2
Bright dot	Display Area	Total		Note1														
	$N \leq 2$	$N \leq 2$																
Dark dot	$N \leq 4$	$N \leq 4$																
Total dot	$N \leq 4$	$N \leq 4$																
Mura	Not visible through 5% ND filters.		Note 2															
03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 <table><tr><th>Length</th><th>Width</th><th>Acc. Qty</th></tr><tr><td>/</td><td>$W \leq 0.1$</td><td>Ignore</td></tr><tr><td>$L \leq 2.5$</td><td>$0.1 < W \leq 0.2$</td><td>3</td></tr><tr><td>$L > 2.5$</td><td>$0.2 < W$</td><td>0</td></tr><tr><td colspan="2">Total</td><td>3</td></tr></table> Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.	Length	Width	Acc. Qty	/	$W \leq 0.1$	Ignore	$L \leq 2.5$	$0.1 < W \leq 0.2$	3	$L > 2.5$	$0.2 < W$	0	Total		3	
Length	Width	Acc. Qty																
/	$W \leq 0.1$	Ignore																
$L \leq 2.5$	$0.1 < W \leq 0.2$	3																
$L > 2.5$	$0.2 < W$	0																
Total		3																
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.																

05	Glass Chipping Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$			
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	3											
$a < \text{Glass Thickness}$												
06	Glass Chipping Rear of Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	Glass Chipping Except Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	Glass Corner Chipping: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												

09	Glass Burr: (Minor defect) 	<table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>$F < 1.0$</td><td>Ignore</td></tr></table> Glass burr don't affect assemble and module dimension.	Length	Acc. Qty	$F < 1.0$	Ignore				
Length	Acc. Qty									
$F < 1.0$	Ignore									
10	FPC Defect: (Minor defect) 	10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.								
11	Bubble on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.30$</td><td>Ignore</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>$N \leq 2$</td></tr><tr><td>$0.50 < \varphi$</td><td>$N = 0$</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.30$	Ignore	$0.30 < \varphi \leq 0.50$	$N \leq 2$	$0.50 < \varphi$	$N = 0$
Diameter	Acc. Qty									
$\varphi \leq 0.30$	Ignore									
$0.30 < \varphi \leq 0.50$	$N \leq 2$									
$0.50 < \varphi$	$N = 0$									
12	Dent on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.25$</td><td>Ignore</td></tr><tr><td>$0.25 < \varphi \leq 0.50$</td><td>$N \leq 4$</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.25$	Ignore	$0.25 < \varphi \leq 0.50$	$N \leq 4$	$0.50 < \varphi$	None
Diameter	Acc. Qty									
$\varphi \leq 0.25$	Ignore									
$0.25 < \varphi \leq 0.50$	$N \leq 4$									
$0.50 < \varphi$	None									
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.								
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.								

15	Soldering	Follow IPC-A-610C standard
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

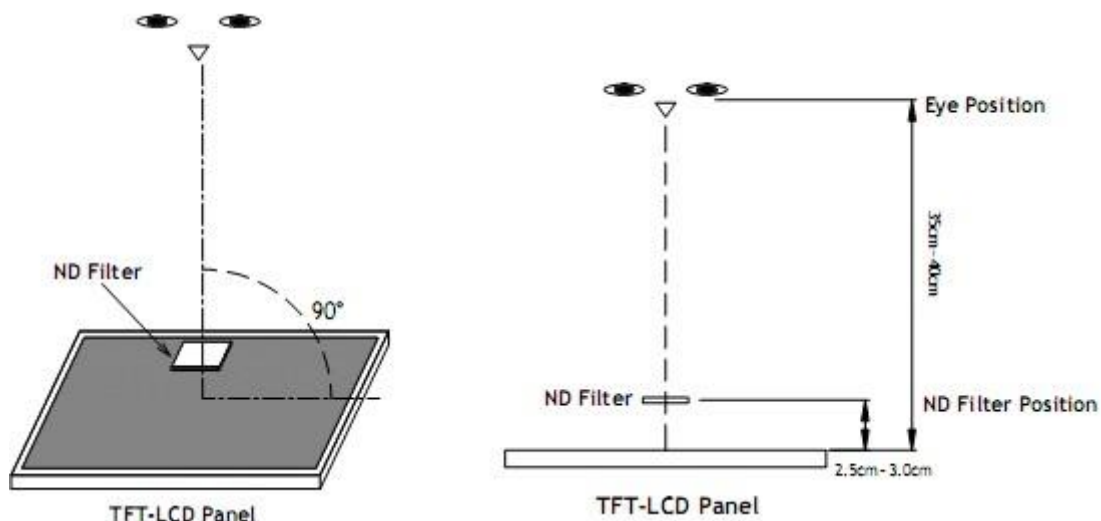
10.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packaging

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	-	GB/T5170.14-2009
8	Electrical Static Discharge	Air: ±8KV 150pF/330Ω 5 times Contact: ±4KV 150pF/330Ω 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8-1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2.Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter

12.4.Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

- 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

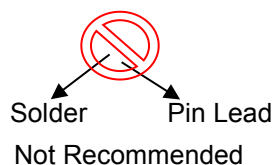
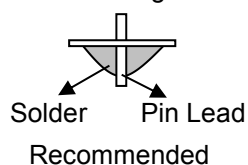
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290℃

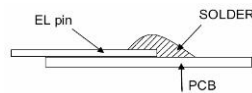
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

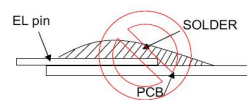
- 12.4.2.4. No horizontal press on the EL leads during soldering.

- 12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting

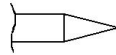


Recommended

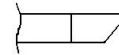


Not Recommended

12.4.2.7. The type of the solder iron:

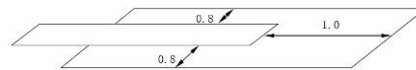


Recommended



Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. *Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.*

12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD

14. Outline Drawing

